LNJ8L4C18RAA

Surface Mounting Chip LED

3528 (PLCC4) Type

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	190	mW
Forward current	I_F	70	mA
Pulse forward current *	I_{FP}	100	mA
Reverse voltage	V_R	5	V
Junction temperature	T_j	125	°C
Thermal resistance	R_{th}	130	°C/W
Operating ambient temperature	T_{opr}	–40 to +105	°C
Storage temperature	T_{stg}	–40 to +125	°C

Note) ∗: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

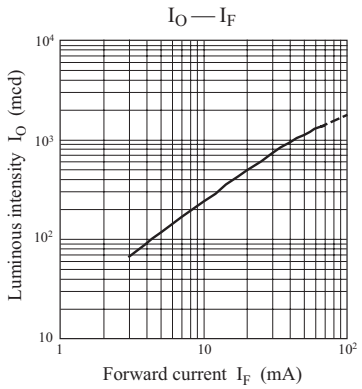
■ Lighting Color

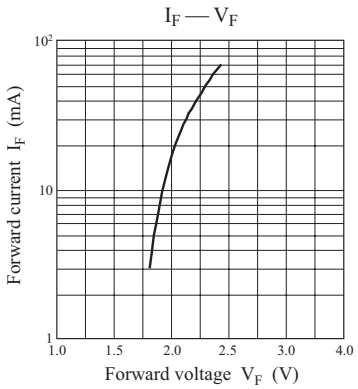
- Red

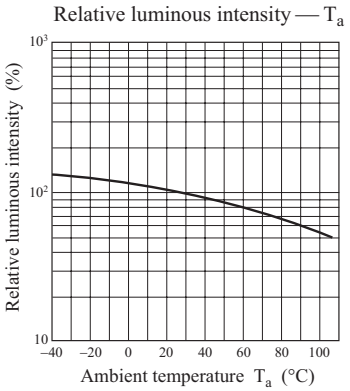
■ Electro-Optical Characteristics $T_a = 25°C \pm 3°C$

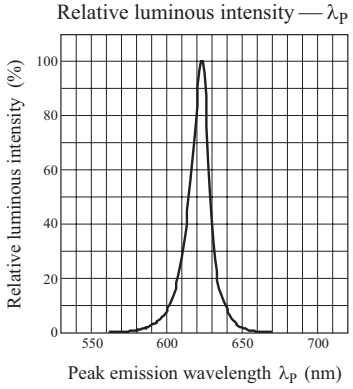
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	I_O	I_F = 50 mA	900	1130	1450	mcd
Reverse current	I_R	V_R = 5 V			10	μA
Forward voltage *2	V_F	I_F = 50 mA	2.05	2.30	2.65	V
Luminous flux *1	F	I_F = 50 mA	(3.36)	(4.20)	(5.40)	lm
Peak emission wavelength	λ_P	I_F = 50 mA		623		nm
Dominant emission wavelength *3	λ_d	I_F = 50 mA	612	617	624	nm
Spectral half band width	$\Delta\lambda$	I_F = 50 mA		20		nm

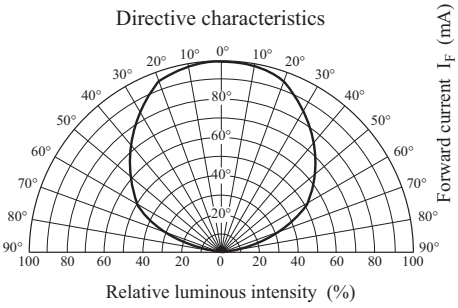
Note) ∗1: Measurement tolerance: ±11%
∗2: Measurement tolerance: ±0.15 V
∗3: Measurement tolerance: ±2 nm

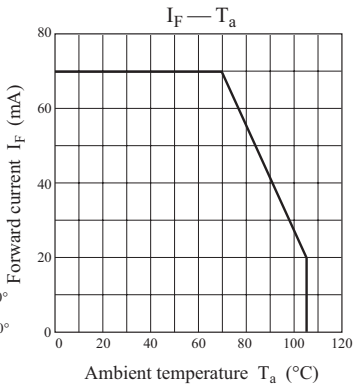






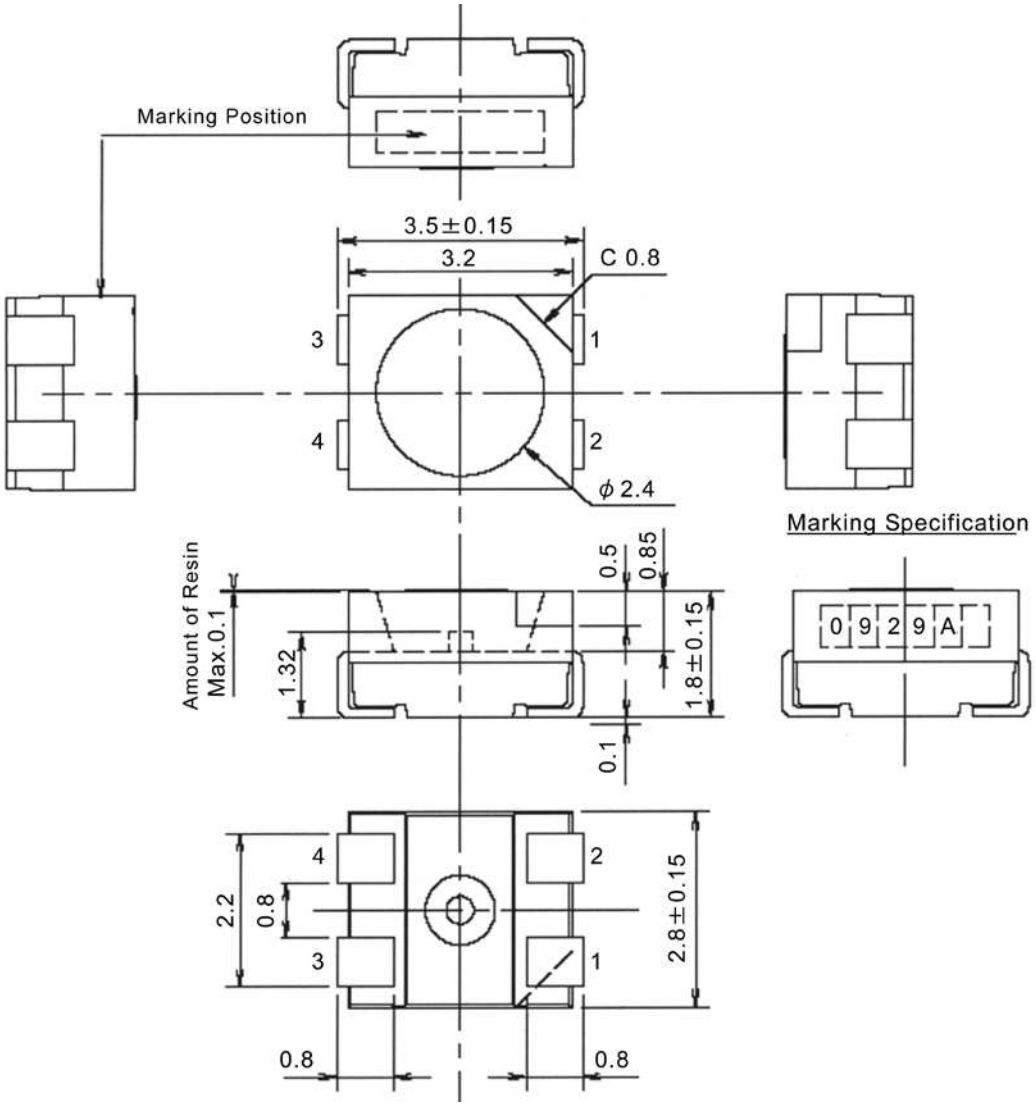






■ Package (Unit: mm)

LLDFTR4JL400



- Pin name
  1: Cathode
  2: Anode
  3: N.C.
  4: Anode

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